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EFS ID: 53694

Application ID: 10667227



Title of Invention: SEMICONDUCTOR PACKAGE AND
METHOD OF MAKING
LEADFRAME HAVING LEAD
LOCKS TO SECURE LEADS TO
ENCAPSULANT

First Named Inventor: Jae Yee

Domestic/Foreign Application: Domestic Application

Filing Date: 2003-09-18

Effective Receipt Date: 2004-01-14

Submission Type: Information Disclosure
Statement

Filing Type:

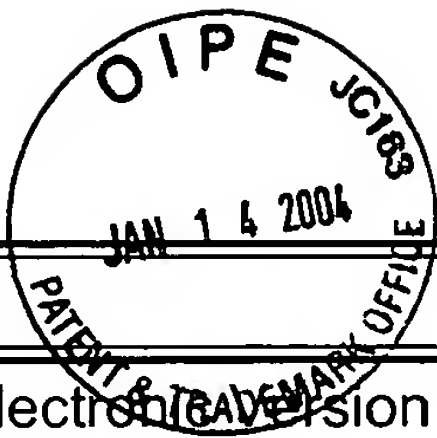
Confirmation number: 7012

Attorney Docket Number: AMKOR012G1

Total Fees Authorized:

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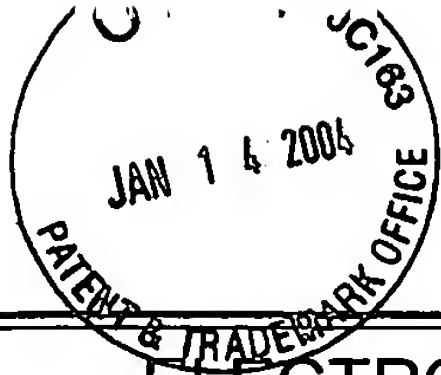


TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0


Title of Invention	SEMICONDUCTOR PACKAGE AND METHOD OF MAKING LEADFRAME HAVING LEAD LOCKS TO SECURE LEADS TO ENCAPSULANT									
Application Number: 10/667227 										
Date: 2003-09-18										
First Named Applicant: Jae Hak Yee										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
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<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids5-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids5-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
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	us-ids.dtd									
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Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

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<h3>US Patent Documents</h3> <p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td></td><td>1</td><td>6194777</td><td>2001-02-27</td><td>ABBOTT ET AL</td><td></td><td></td><td></td></tr><tr><td></td><td>2</td><td>6198171</td><td>2001-03-06</td><td>HUANG ET AL</td><td></td><td></td><td></td></tr><tr><td></td><td>3</td><td>6197615</td><td>2001-03-06</td><td>SONG ET AL</td><td></td><td></td><td></td></tr><tr><td></td><td>4</td><td>6201292</td><td>2001-03-13</td><td>YAGI ET AL</td><td></td><td></td><td></td></tr><tr><td></td><td>5</td><td>6201186</td><td>2001-03-13</td><td>DANIELS ET AL</td><td></td><td></td><td></td></tr><tr><td></td><td>6</td><td>6204554</td><td>2001-03-20</td><td>EWER ET AL</td><td></td><td></td><td></td></tr><tr><td></td><td>7</td><td>6208023</td><td>2001-03-27</td><td>NAKAYAMA ET AL</td><td></td><td></td><td></td></tr><tr><td></td><td>8</td><td>6208021</td><td>2001-03-27</td><td>OHUCHI ET AL</td><td></td><td></td><td></td></tr><tr><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td></tr></tbody></table>		init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass		1	6194777	2001-02-27	ABBOTT ET AL					2	6198171	2001-03-06	HUANG ET AL					3	6197615	2001-03-06	SONG ET AL					4	6201292	2001-03-13	YAGI ET AL					5	6201186	2001-03-13	DANIELS ET AL					6	6204554	2001-03-20	EWER ET AL					7	6208023	2001-03-27	NAKAYAMA ET AL					8	6208021	2001-03-27	OHUCHI ET AL											
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	9	6208020	2001-03-27	MINAMIO
	10	6211462	2001-04-03	CARTER, JR. ET AL
	11	6218731	2001-04-17	HUANG ET AL.
	12	6222258	2001-04-24	ASANO ET AL
	13	6225146	2001-05-01	YAMAGUCHI ET AL
	14	6229205	2001-05-08	JEONG ET AL
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	16	6239384	2001-05-29	SMITH ET AL
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	22	6281568	2001-08-28	GLENN ET AL.
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	32	6303984	2001-10-16	CORISIS
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	35	6316838	2001-11-13	OZAWA ET AL.
	36	6316822	2001-11-13	VENKATESHWARAN ET AL.
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	40	6326243	2001-12-04	SUZUYA ET AL.
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	43	6339255	2002-01-15	SHIN
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	45	6355502	2002-03-12	KANG ET AL.
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	47	6369447	2002-04-09	MORI
	48	6373127	2002-04-16	BAUDOUIN ET AL.
	49	6380048	2002-04-30	BOON ET AL.
	50	6384472	2002-05-07	HUANG

Signature

Examiner Name	Date